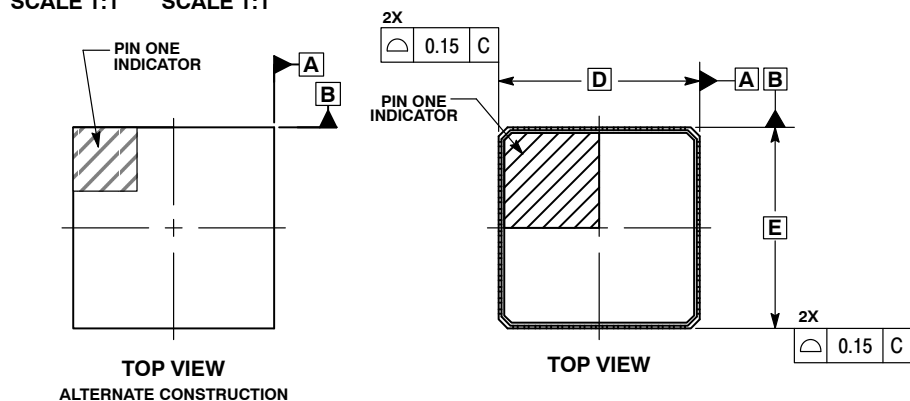

**QFN64 9x9, 0.5P (PUNCH & SAWN)**  
CASE 485DH  
ISSUE O

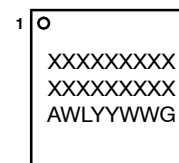
DATE 27 AUG 2013



## NOTES:

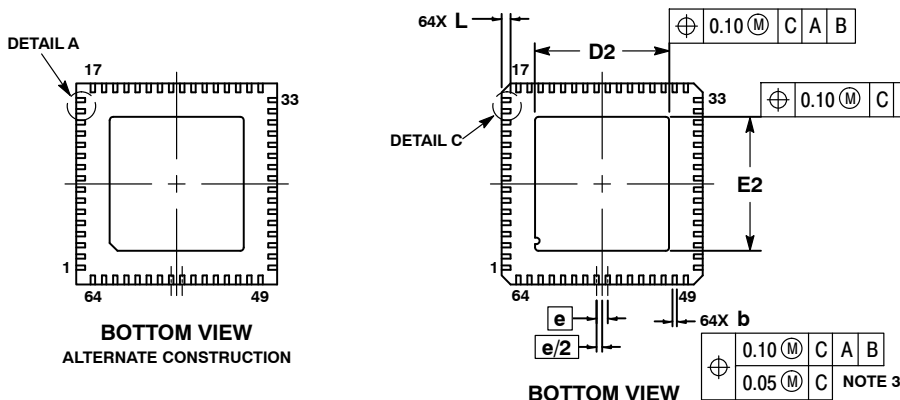
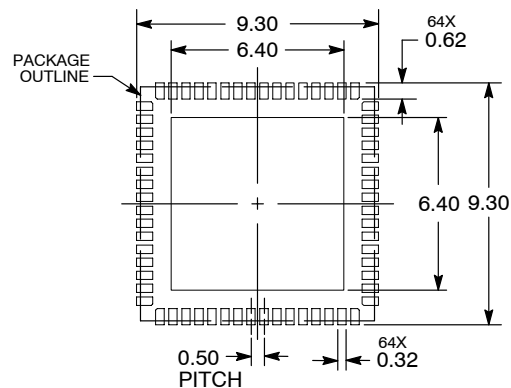
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25mm FROM THE TERMINAL TIP
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. ALL DIMENSIONS APPLY TO BOTH THE SAWN AND PUNCH PACKAGES.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.18	0.30
D	9.00 BSC	
D2	5.90	6.25
E	9.00 BSC	
E2	5.90	6.25
e	0.50 BSC	
L	0.30	0.50
L1	0.00	0.15

**GENERIC MARKING DIAGRAM\***


XXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "•", may or may not be present.


**RECOMMENDED SOLDERING FOOTPRINT**


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<b>DESCRIPTION:</b>	<b>QFN64 9x9, 0.5P (PUNCH &amp; SAWN)</b>	<b>PAGE 1 OF 1</b>

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